



"PATENT"

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF  
Stewart *et al.*

§ EXAMINER: TRAN, Thien F.

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SERIAL NO.: 10/091,086

§ GROUP ART UNIT: 2811

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FILED: March 5, 2002

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§ ATTY. DOCKET NO.: US02022

FOR: Attachment Of Surface Mount  
Devices To Printed Circuit Boards Using A  
Thermoplastic Adhesive

§

DATE: June 24, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**RESPONSE TO RESTRICTION REQUIREMENT**

Sir:

This is a response to the restriction requirement mailed May 26, 2004, for the above referenced application.

In the restriction requirement, the claims of the present application have been restricted as follows:

Group I      Claims 1-3 and 5-55 drawn to a semiconductor device, classified in class 257, subclass 686

Group II      Claims 4 and 56-92 drawn to a process for making semiconductor devices board, classified in class 438, subclass 22+.

The application is further restricted to the following species

Species 1      Embodiment of Figure 1 (claims 1-3)

Species 2      Embodiment of Figure 2 (claims 5-8)

Species 3      Embodiment of Figure 3 (claims 9-55).

Applicants elect to prosecute the claims of Group I (Claims 1-3 and 5-55), species 3, with traverse.

It is respectfully submitted that the subject matter are interrelated such that a search of the multiple surface amount electronic device having the thermoplastic adhesive of Group I would require a search of the class and subclass of Group II. In order to facilitate prosecution, it is respectfully requested that all the claims be examined together.

If it would be of assistance, the Examiner is invited to contact the undersigned.

Date: 6-24-2004

Respectfully submitted,

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